



Material Content Data Sheet



Sales Product Name	SAK-XC2267-96F80L AC			Issued		25. November 2019		
MA#	MA001614910							
Package	PG-LQFP-100-3			Weight*		747.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	40.856	5.46	5.46	54637	54637
leadframe	inorganic material	phosphorus	7723-14-0	0.067	0.01		90	
	non noble metal	zinc	7440-66-6	0.270	0.04		361	
	non noble metal	iron	7439-89-6	5.396	0.72		7216	
	non noble metal	copper	7440-50-8	219.094	29.30	30.07	292997	300664
wire	noble metal	gold	7440-57-5	4.246	0.57	0.57	5678	5678
encapsulation	organic material	carbon black	1333-86-4	2.290	0.31		3063	
	plastics	epoxy resin	-	61.833	8.27		82690	
	inorganic material	silicondioxide	60676-86-0	393.897	52.67	61.25	526763	612516
leadfinish	non noble metal	tin	7440-31-5	8.282	1.11	1.11	11076	11076
plating	noble metal	silver	7440-22-4	1.060	0.14	0.14	1418	1418
glue	plastics	epoxy resin	-	2.619	0.35		3503	
	noble metal	silver	7440-22-4	7.858	1.05	1.40	10508	14011
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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